Nch 600V 20A Power MOSFET

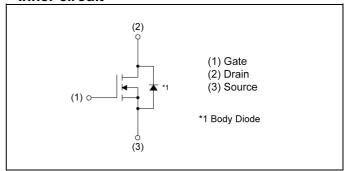
V _{DSS}	600V
R _{DS(on)} (Max.)	0.196Ω
I _D	±20A
P _D	231W

Outline TO-247

Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Parallel use is easy
- 4) Pb-free lead plating; RoHS compliant

•Inner circuit



Application

Switching

Packaging specifications

Packing	Tube
Packing code	C13
Marking	R6020KNZ4
Quantity (pcs)	600

ullet Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V _{DSS}	600	V
Continuous drain current (T _c = 25°C)		I _D *1	±20	Α
Pulsed drain current		I _{DP} *2	±60	Α
Cata Sauma valtaga	static	V	±20	V
Gate - Source voltage	AC(f>1Hz)	V _{GSS}	±30	V
Avalanche current, single pulse	·	I _{AS}	3.4	Α
Avalanche energy, single pulse		E _{AS} *3	418	mJ
Power dissipation (T _c = 25°C)	P _D	231	W	
Junction temperature	T _j	150	°C	
Operating junction and storage tempera	ature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Downwortow	Cymah al	Values			1.1:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *4	-	-	0.54	°C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	30	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

• Electrical characteristics $(T_a = 25^{\circ}C)$

Parameter	Cumb al	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		600	-	-	V
		V _{DS} = 600V, V _{GS} = 0V				
Zero gate voltage drain current	I _{DSS}	$T_j = 25^{\circ}C$	-	-	100	μΑ
		$T_j = 125^{\circ}C$	-	-	1000	
Gate - Source leakage current	I _{GSS}	V_{GS} = ±20V, V_{DS} = 0V	1	-	±100	nA
Gate threshold voltage	$V_{GS(th)}$	V_{DS} = 10V, I_D = 1mA	3	-	5	V
		V _{GS} = 10V, I _D = 9.5A				
Static drain - source on - state resistance	R _{DS(on)} *5	$T_j = 25^{\circ}C$	-	0.170	0.196	Ω
		$T_j = 125^{\circ}C$	-	-	-	
Gate resistance	R_{G}	f = 1MHz, open drain	-	2.3	-	Ω

● Electrical characteristics (T_a = 25°C)

Darameter	Cymahal	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Urill	
Input capacitance	C _{iss}	V _{GS} = 0V	-	1550	-		
Output capacitance	C _{oss}	V _{DS} = 25V	-	1350	-	pF	
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	55	-		
Turn - on delay time	$t_{d(on)}^{*5}$	$V_{DD} \simeq 300V$, $V_{GS} = 10V$	-	30	1		
Rise time	t _r *5	I _D = 10A	-	30	-		
Turn - off delay time	t _{d(off)} *5	$R_L \simeq 30\Omega$	-	55	-	ns	
Fall time	t _f *5	$R_G = 10\Omega$	-	10	-		

● Gate charge characteristics (T_a = 25°C)

Davamatar	Company of	Conditions	Values			1.1:4
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q_g^{*5}	V _{DD} ≈ 300V	-	40	-	
Gate - Source charge	Q _{gs} *5	I _D = 20A	-	12	-	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 10V	-	15	-	
Gate plateau voltage	V _(plateau)	V _{DD} ≈ 300V, I _D = 20A	-	6.4	-	V

^{*1} Limited only by maximum channel temperature allowed

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \doteqdot 70mH, V_{DD}=50V, R_G=25 Ω , Starting T_j=25°C

^{*4} T_C=25°C

^{*5} Pulsed

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Source current	I _S *1	· T _C = 25°C	1	-	20	Α	
Pulsed source current	I _{SP} *2	1C - 23 C	1	-	60	Α	
Source-Drain voltage	V _{SD} *5	$V_{GS} = 0V, I_{S} = 20A$	-	-	1.5	V	
Reverse recovery time	t _{rr} *5		-	500	-	ns	
Reverse recovery charge	Q _{rr} *5	I _S = 20A di/dt = 100A/μs	-	7.5	-	μC	
Peak reverse recovery current	_{rr} *5		-	30	-	Α	

Fig.1 Power Dissipation Derating Curve

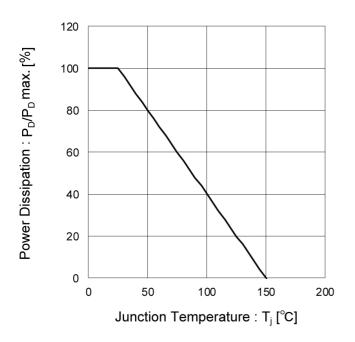


Fig.2 Drain Current Derating Curve

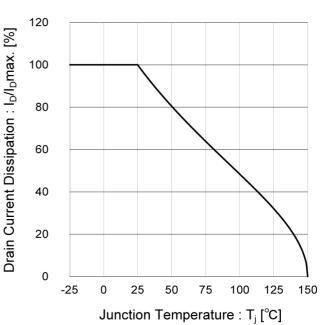


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

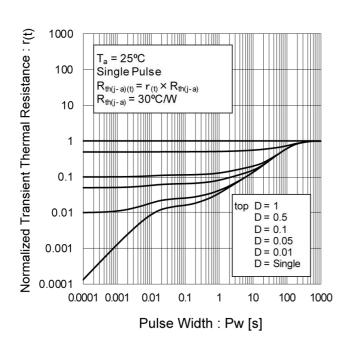
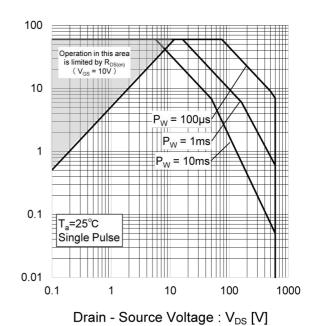


Fig.4 Maximum Safe Operating Area



Drain Current : I_D [A]

Fig.5 Avalanche Energy Derating
Curve vs. Junction Temperature

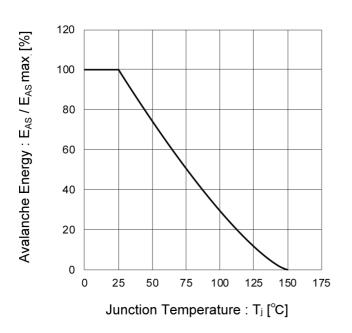


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

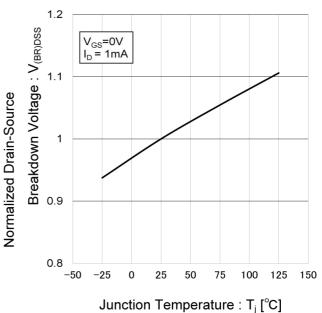


Fig.7 Typical Output Characteristics(I)

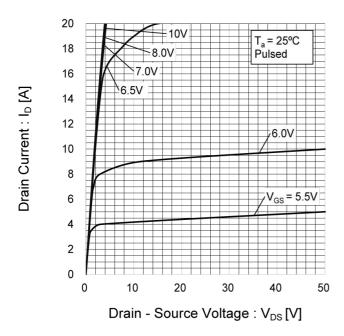
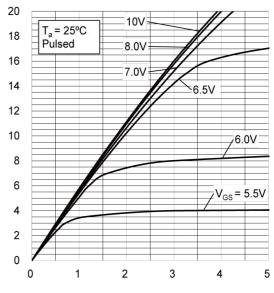


Fig.8 Typical Output Characteristics(II)



Drain - Source Voltage: V_{DS}[V]

Drain Current : I_D [A]

Fig.9 Typical Transfer Characteristics

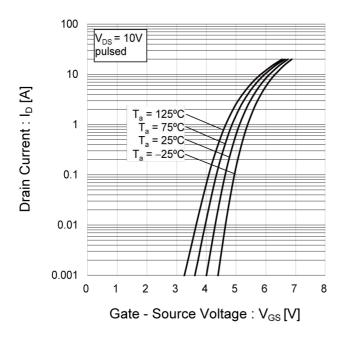


Fig.10 Gate Threshold Voltage vs. Junction Temperature

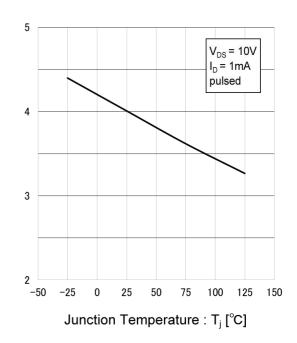


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

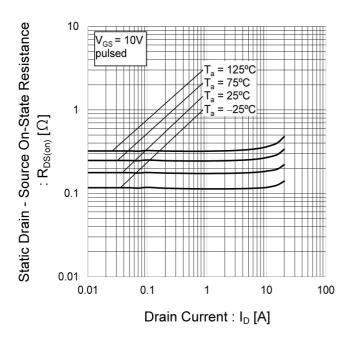
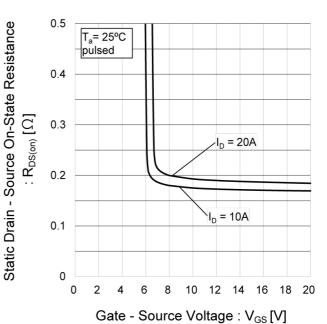


Fig.12 Static Drain - Source On - State Resistance vs. Gate - Source Voltage



Gate Threshold Voltage: V_{GS(th)} [V]

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

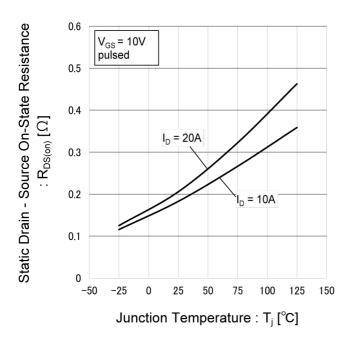


Fig.14 Typical Capacitance vs.
Drain - Source Voltage

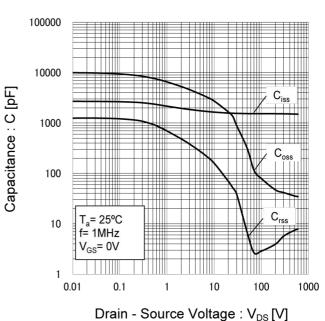


Fig.15 Switching Characteristics

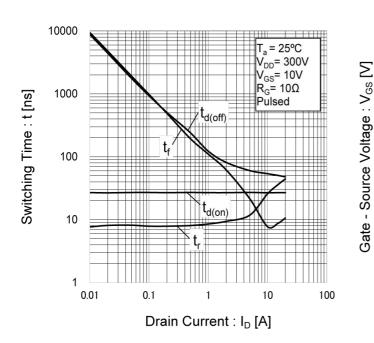


Fig.16 Typical Gate Charge

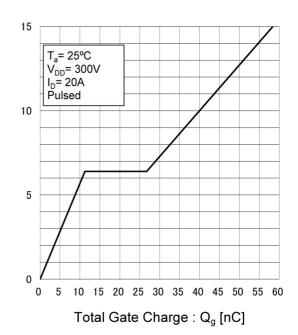
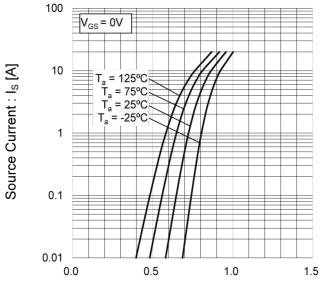
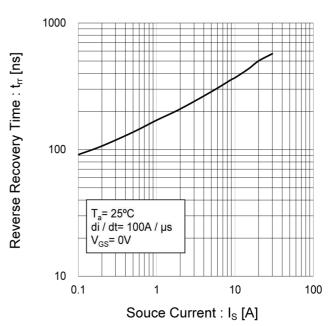


Fig.17 Source Current vs. Source - Drain Voltage



Source - Drain Voltage : V_{SD} [V]

Fig.18 Reverse Recovery Time vs. Source Current



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

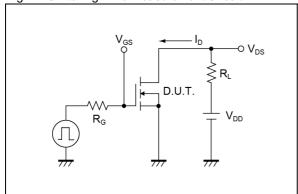


Fig.2-1 Gate Charge Measurement Circuit

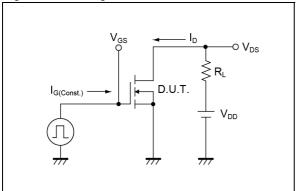


Fig.3-1 Avalanche Measurement Circuit

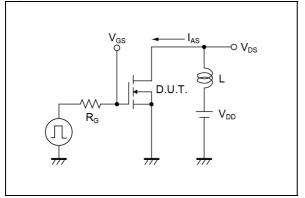


Fig.4-1 trr Measurement Circuit

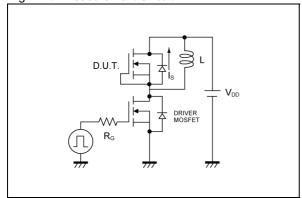


Fig.1-2 Switching Waveforms

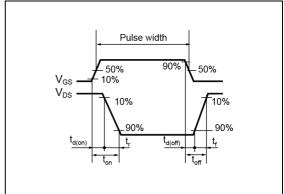


Fig.2-2 Gate Charge Waveform

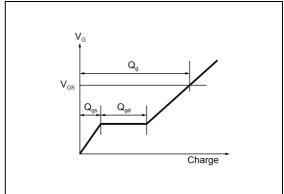


Fig.3-2 Avalanche Waveform

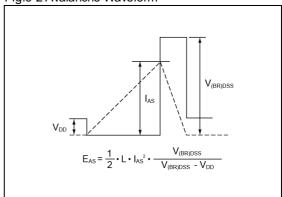
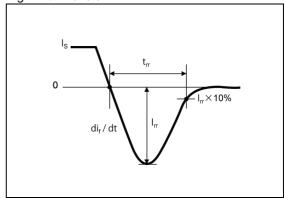
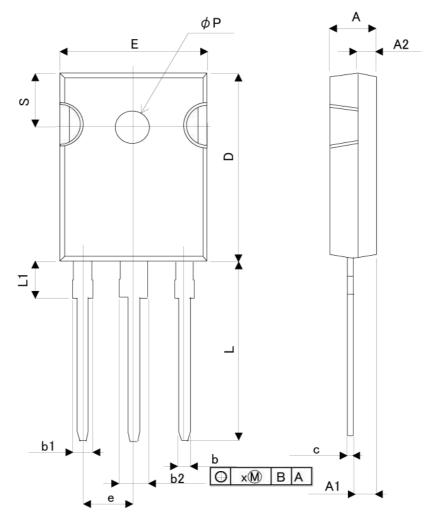


Fig.4-2 trr Waveform



Dimensions

TO-247



DIM	MILIME	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.82	5.22	0.190	0.206
A1	2.11	2.71	0.083	0.107
A2	1.80	2.20	0.071	0.087
b	1.00	1.40	0.039	0.055
b1	1.80	2.20	0.071	0.087
b2	2.80	3.20	0.110	0.126
С	0.45	0.75	0.018	0.030
D	20.65	21.25	0.813	0.837
E	15.64	16.24	0.616	0.639
е	5.4	14	0.2	14
L	19.77	20.37	0.778	0.802
L1	4.09	4.29	0.161	0.169
Р	3.51	3.71	0.138	0.146
S	5.97	6.37	0.235	0.251

Dimension in mm/inches



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CLASSⅢ	CLASSⅢ	CLASS II b	CLASSⅢ
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
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- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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